

High Density Cell Design For Ultra Low On-Resistance

Fully Characterized Avalanche Voltage and Current

Advanced Trench Process Technology

Improved Shoot-Through FOM

SO-8 Package Design

## **GENERAL DESCRIPTION**

The CMT4953G provide the designer with the best combination of fast switching , ruggedized device design , low on-resistance and cost-effectiveness.

The SOP-8 package is universally preferred for all commercial-industrial mount applications and suited for low voltage applications such as DC/DC converters.

#### **APPLICATIONS**

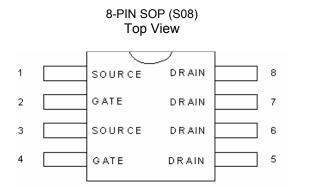
- Power Management in Notebook
- Portable Equipment
- Battery Powered System
- DC/DC Converter
- Load Switch
- DSC
- ♦ LCD Display inverter

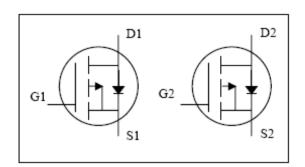
# **PIN CONFIGURATION**

# SYMBOL

**FEATURES** 

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#### P-Channel MOSFET

## **ORDERING INFORMATION**

Part Number	Package
CMT4953G	SOP-8

\*Note: G : Suffix for Pb Free Product



# **ABSOLUTE MAXIMUM RATINGS**

Rating		Symbol	Value	Unit
Drain- Source Voltage		V <sub>DS</sub>	-30	V
Gate- Source Voltage		V <sub>GS</sub>	±20	V
Continuous Drain Current <sup>1</sup>	T <sub>A</sub> =25℃	Ι <sub>D</sub>	-4.5	А
Pulsed Drain Current <sup>2</sup>			-23	A
Total Power Dissipation <sup>1</sup>	T <sub>A</sub> =25℃	PD	2	W
Operating Junction Temperature Range			-55 to150	°C
Storage Temperature Range		T <sub>STG</sub>	-55 to 150	°C
Linear Derating Factor			0.02	°C <b>/W</b>
Thermal Resistance Junction-ambient <sup>1</sup> (Max)		Rthj-amb	62.5	°C/W



#### **ELECTRICAL CHARACTERISTICS**

Unless otherwise specified,  $T_{\rm J}$  = 25  $^\circ\!{\rm C}$  . (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =-250uA	-30	-	-	V
<b>D</b>		V <sub>GS</sub> =-10V, I <sub>D</sub> =-4.6A	-	-	55	m $\Omega$
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistancem <sup>2</sup>	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-3.6A	-	-	90	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS}=V_{GS}$ , $I_{D}=-250$ uA	-1	-	-2.5	V
9fs	Forward Transconductance <sup>2</sup>	V <sub>DS</sub> =-5V, I <sub>D</sub> =-4.6A	-	5	-	S
I <sub>DSS</sub>	Drain-Source Leakage Current (Tj=25 C)	V <sub>DS</sub> =-24V, V <sub>GS</sub> =0V	-	-	-1	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V	-	-	±100	nA
Qg	Total Gate Charge <sup>2</sup>	I <sub>D</sub> =-4.6A	-	11.7	-	nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>DS</sub> =-15V	-	2.1	-	nC
Q <sub>gd</sub>	Gate-Drain ("Miller") Charge	V <sub>GS</sub> =-10V	-	2.9	-	nC
t <sub>d(on)</sub>	Turn-on Delay Time <sup>2</sup>	V <sub>DS</sub> =-15V	-	9	-	ns
t <sub>r</sub>	Rise Time	I <sub>D</sub> =-1A	-	10	-	ns
t <sub>d(off)</sub>	Turn-off Delay Time	R <sub>G</sub> =6Ω,V <sub>GS</sub> =-10V	-	37	-	ns
t <sub>f</sub>	Fall Time	R <sub>D</sub> =15 <b>Ω</b>	-	23	-	ns
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V	-	582	-	pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> =-15V	-	125	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	f=1.0MHz	-	86	-	pF

# Source-Drain Diode

	Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
V	SD	Forward On Voltage <sup>2</sup>	I <sub>S</sub> =-1.7A, V <sub>GS</sub> =0V	-	-0.84	-1.2	V

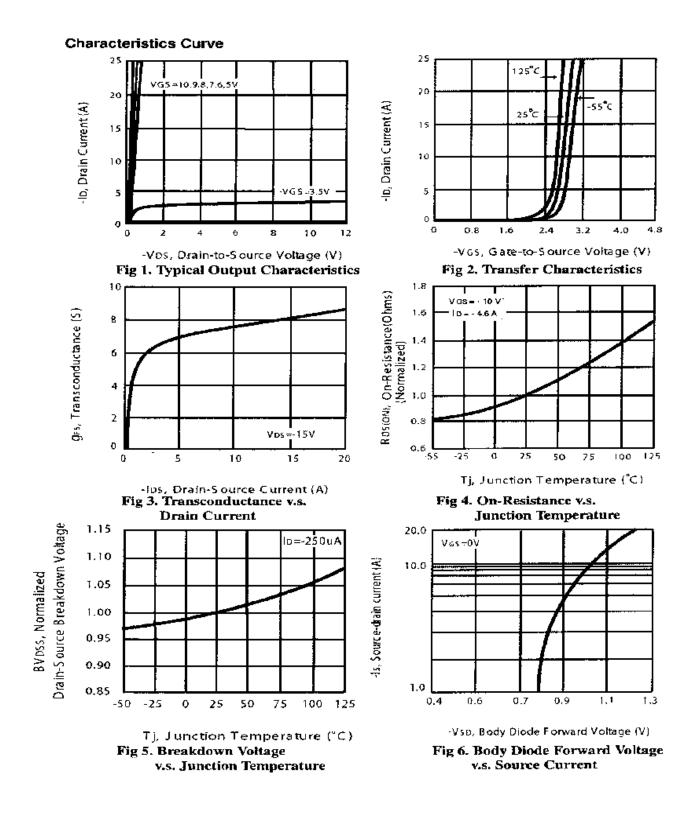
#### Notes:

1.Surface mounted on FR4 Board ,  $t{\leq}2\%$ 

2.Pulse width  $\ \leq 300 \text{us}$  , duty cycle  $\ \leq 2\%.$ 



# TYPICAL CHARACTERISTICS





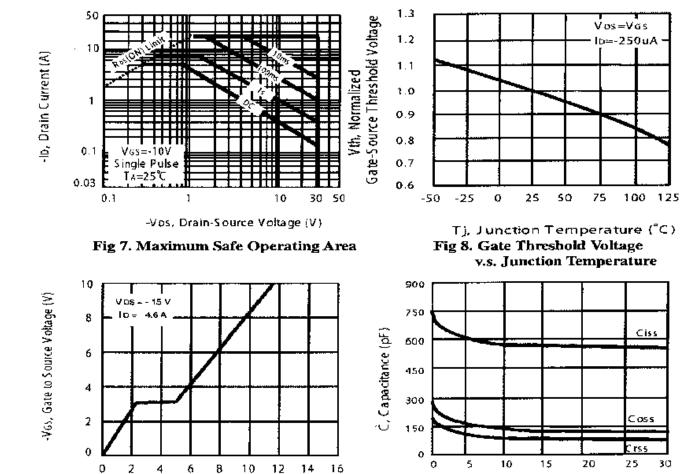


Fig 9. Gate Charge Characteristics

Qg, Total Gate Charge (nC)

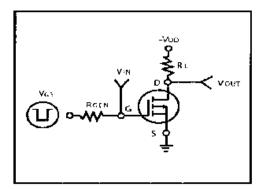


Fig 11. Switching Time Circuit

Fig 10. Typical Capacitance Characteristics

-Vos, Drain-to Source Voltage (V)

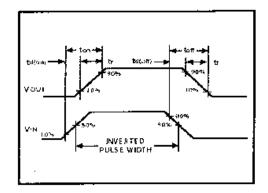


Fig 12. Switching Time Waveform

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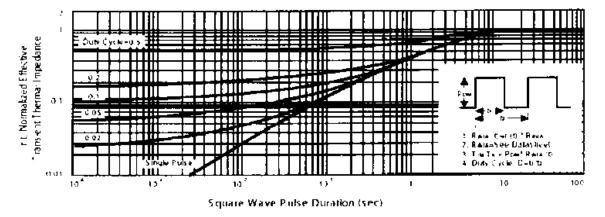
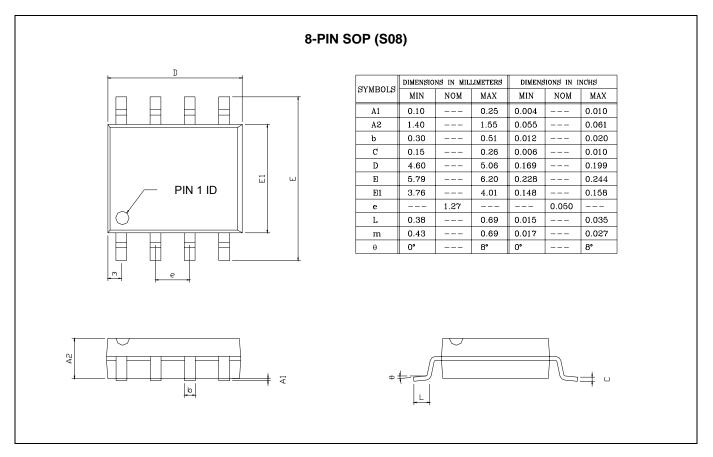


Fig 13. Normalized Thermal Transient Impedance Curve

## PACKAGE DIMENSION





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